

### Product Overview

The TQP0104 is a wide band over-molded QFN discrete GaN power amplifier. The device is a single stage unmatched power amplifier transistor.

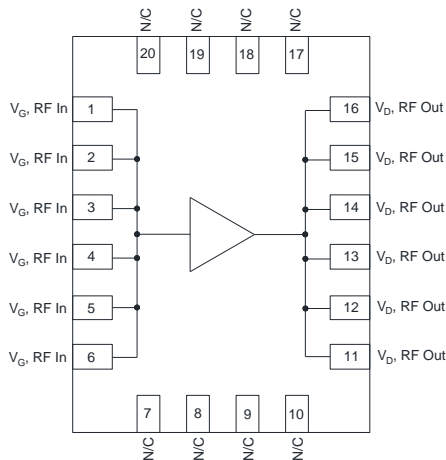
The TQP0104 can be used in Doherty architecture for the final stage of a base station power amplifier for small cell, microcell, and active antenna systems. The TQP0104 can also be used as a driver in a macrocell base station power amplifier.

The wide bandwidth of the TQP0104 makes it suitable for many different applications from DC to 4 GHz. TQP0104 can deliver  $P_{SAT}$  of 30 W at 28 to 32 V operation.

The device is housed in an industry-standard 3 x 4 mm surface mount QFN package.

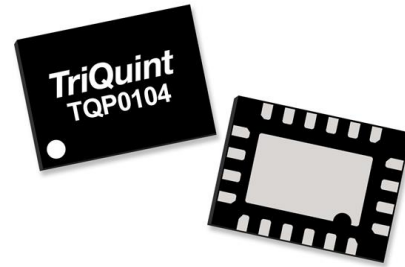
Lead-free and ROHS compliant

### Functional Block Diagram



### Pad Configuration

Pad No.	Symbol
1-6	RF IN, $V_G$
7-10, 17-20	N/C
11-16	RF OUT, $V_D$
Backside Paddle	RF/DC GND



### Key Features

- Frequency: DC to 4.0 GHz
- Output Power ( $P_{3dB}$ )<sup>1</sup>: 30.0 W
- Linear Gain<sup>1</sup>: 17.0 dB
- Typical PAE<sub>3dB</sub><sup>1</sup>: 64.0%
- Operating Voltage: 32 V
- Low thermal resistance package
- CW and Pulse capable
- 3 x 4 x 0.85 mm package

Note 1: @ 2.6 GHz

### Applications

- Macrocell Base Station Driver
- Microcell Base Station
- Small Cell Final Stage
- Active Antenna
- General Purpose Applications
- Military and Civilian radar
- Land mobile and military radio communications
- Test instrumentation
- Wideband and narrowband amplifiers
- Jammers

### Ordering Information

Part Number	Description
TQP0104	30W, DC-4GHz, 250 Piece 13" Reel
TQP0104-2.6-EVB	2.5-2.7 GHz Eval Board
TQP0104-2.1-DOH	2.1 GHz Doherty Eval Board

## Absolute Maximum Ratings

Parameter	Rating
Drain to Gate Voltage ( $V_{DG}$ )	100 V
Gate Voltage Range ( $V_G$ )	-7 to +2 V
RF Input Power Over Drive above $P_{IN}$ at 36 dBm $P_{OUT}$ , 50 $\Omega$ , $T = 25^\circ\text{C}$	8 dB
VSWR Mismatch, P1dB Pulse (20% duty cycle, 100 $\mu\text{s}$ width), $T = 25^\circ\text{C}$	10:1
Storage Temperature	-65 to 150°C

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability.

## Recommended Operating Conditions

Parameter	Value	Units
Drain Voltage Range ( $V_D$ )	32 (Typ.)	V
Drain Quiescent Current ( $I_{DQ}$ )	70	mA
Peak Drain Current ( $I_D$ )	1800 (Typ.)	mA
Gate Voltage ( $V_G$ ) <sup>1</sup>	-2.8 (Typ.)	V

Electrical specifications are measured at specified test conditions. Specifications are not guaranteed over all recommended operating conditions.

Note:

- To be adjusted to desired  $I_{DQ}$

## RF Characterization – Simulated Performance CW <sup>(1)</sup>

Parameter	Conditions <sup>(1)</sup>	Typical Value				Units
		2	2.5	3.0	3.5	
Frequency		2	2.5	3.0	3.5	GHz
$V_D$		32	32	32	32	V
$I_{DQ}$		65	65	65	65	mA
$G_{LIN}$	Power Tuned	19.1	17.4	16.3	15.3	dB
Output $P_{1dB}$	Power Tuned	43.8	43.7	43.6	43.4	dBm
$PAE_{1dB}$	Power Tuned	70.6	63	62.3	62.5	%
$G_{1dB}$	Power Tuned	18.1	16.4	15.3	14.3	dB

Notes:

- Test conditions unless otherwise noted:  $T_A = +25^\circ\text{C}$

## RF Characterization – Test Performance at 2.6 GHz

Symbol	Parameter	Min	Typical	Max	Units
$P_{3dB}$	Output Power at 1 dB Gain Compression		21.4		W
$DrE_{3dB}$	Drain Efficiency at 3 dB Gain Compression		65		%
$G_{3dB}$	Gain at 3 dB Compression		14.3		dB

Notes:

- Test conditions unless otherwise noted:  $T_A = 25^\circ\text{C}$ ,  $V_D = 32\text{ V}$ ,  $I_{DQ} = 60\text{ mA}$ , Signal: 100 $\mu\text{s}$  Pulse Width, 20% Duty Cycle

## Electrical Characterization

Symbol	Parameter	Min	Typical	Max	Units
Gate Leakage	$V_D = +10\text{ V}$ , $V_G = -3.7\text{ V}$	-7.56			mA

### Thermal and Reliability Information - CW <sup>(1)</sup>

Parameter	Test Conditions	Value	Units
Thermal Resistance, Peak IR Surface Temperature at Average Power ( $\theta_{JC}$ )	$P_{DISS} = 11.3 \text{ W}$ , $T_{baseplate} = 85^\circ\text{C}$	3.2	$^\circ\text{C/W}$
Channel Temperature, $T_{CH}$		121	$^\circ\text{C}$
Thermal Resistance, Peak IR Surface Temperature at Average Power ( $\theta_{JC}$ )	$P_{DISS} = 15.1 \text{ W}$ , $T_{baseplate} = 85^\circ\text{C}$	3.3	$^\circ\text{C/W}$
Channel Temperature, $T_{CH}$		126	$^\circ\text{C}$
Thermal Resistance, Peak IR Surface Temperature at Average Power ( $\theta_{JC}$ )	$P_{DISS} = 18.9 \text{ W}$ , $T_{baseplate} = 85^\circ\text{C}$	3.3	$^\circ\text{C/W}$
Channel Temperature, $T_{CH}$		148	$^\circ\text{C}$
Thermal Resistance, Peak IR Surface Temperature at Average Power ( $\theta_{JC}$ )	$P_{DISS} = 22.7 \text{ W}$ , $T_{baseplate} = 85^\circ\text{C}$	3.4	$^\circ\text{C/W}$
Channel Temperature, $T_{CH}$		162	$^\circ\text{C}$
Thermal Resistance, Peak IR Surface Temperature at Average Power ( $\theta_{JC}$ )	$P_{DISS} = 30.2 \text{ W}$ , $T_{baseplate} = 85^\circ\text{C}$	3.6	$^\circ\text{C/W}$
Channel Temperature, $T_{CH}$		194	$^\circ\text{C}$

**Notes:**

1. Thermal resistance measured to bottom of package.
2. Refer to the following document: [GaN Device Channel Temperature, Thermal Resistance, and Reliability Estimates](#)

### Thermal and Reliability Information - Pulsed <sup>(1)</sup>

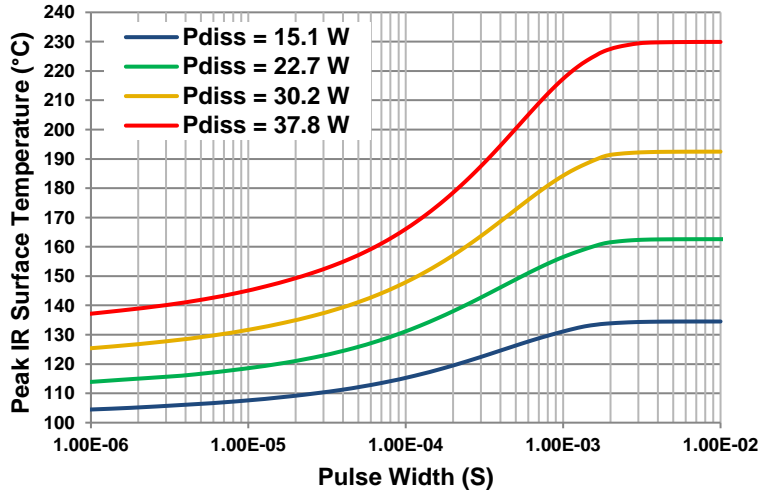
Parameter	Test Conditions	Value	Units
Thermal Resistance, Peak IR Surface Temperature at Average Power ( $\theta_{JC}$ )	$P_{DISS} = 15.1 \text{ W}$ , $T_{baseplate} = 85^\circ\text{C}$ Pulse Width = 100 $\mu\text{S}$	2.0	$^\circ\text{C/W}$
Channel Temperature, $T_{CH}$		Duty Cycle = 5%	115
Thermal Resistance, Peak IR Surface Temperature at Average Power ( $\theta_{JC}$ )	$P_{DISS} = 22.7 \text{ W}$ , $T_{baseplate} = 85^\circ\text{C}$ Pulse Width = 100 $\mu\text{S}$	2.0	$^\circ\text{C/W}$
Channel Temperature, $T_{CH}$		Duty Cycle = 10%	131
Thermal Resistance, Peak IR Surface Temperature at Average Power ( $\theta_{JC}$ )	$P_{DISS} = 30.2 \text{ W}$ , $T_{baseplate} = 85^\circ\text{C}$ Pulse Width = 100 $\mu\text{S}$	2.1	$^\circ\text{C/W}$
Channel Temperature, $T_{CH}$		Duty Cycle = 20%	148
Thermal Resistance, Peak IR Surface Temperature at Average Power ( $\theta_{JC}$ )	$P_{DISS} = 37.8 \text{ W}$ , $T_{baseplate} = 85^\circ\text{C}$ Pulse Width = 100 $\mu\text{S}$	2.1	$^\circ\text{C/W}$
Channel Temperature, $T_{CH}$		Duty Cycle = 20%	166

**Notes:**

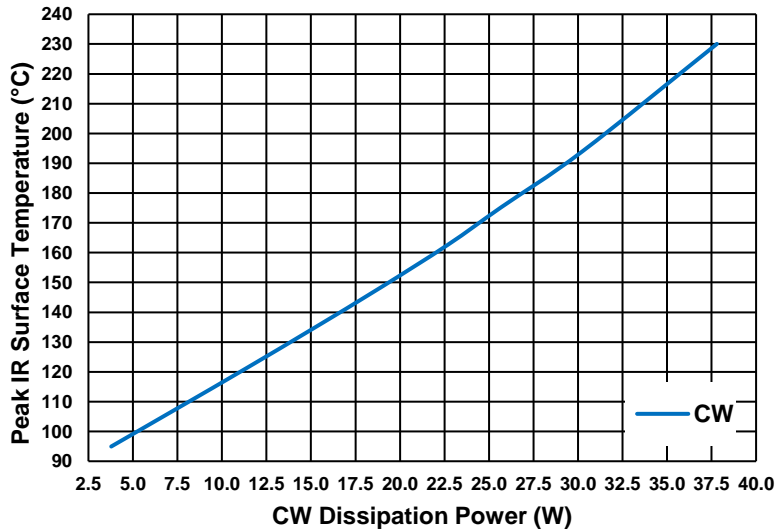
1. Thermal resistance measured to bottom of package.
2. Refer to the following document: [GaN Device Channel Temperature, Thermal Resistance, and Reliability Estimates](#)

Maximum Channel Temperature

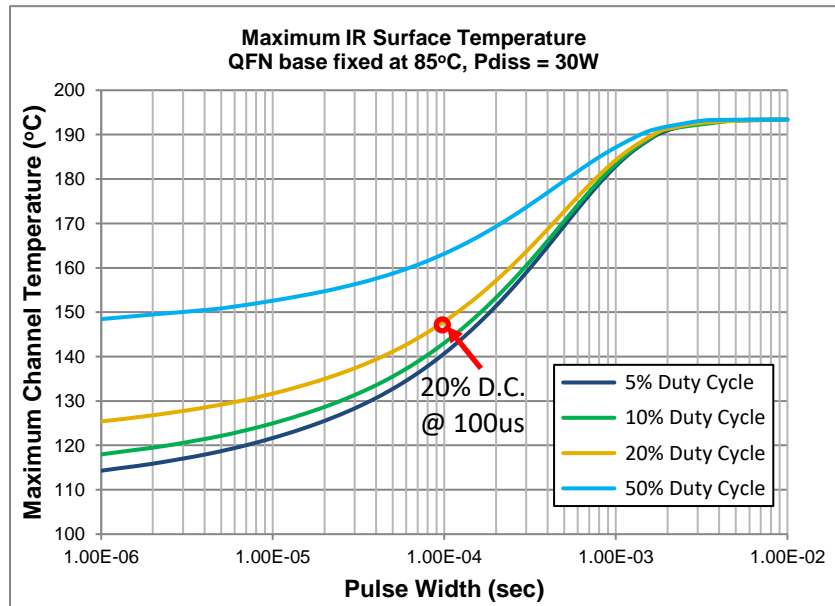
Peak IR Surface Temperature vs. Pulse Width  
QFN Base Fixed at 85 °C, 20% Duty Cycle



Peak IR Surface Temperature vs. CW Dissipation Power  
QFN Base Fixed at 85 °C



Maximum Channel Temperature

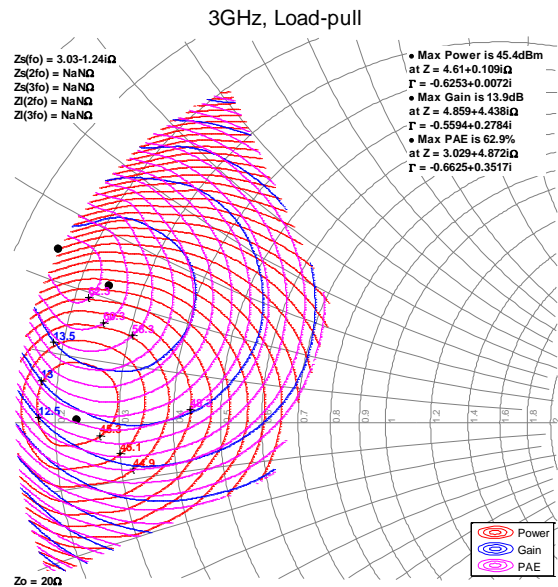
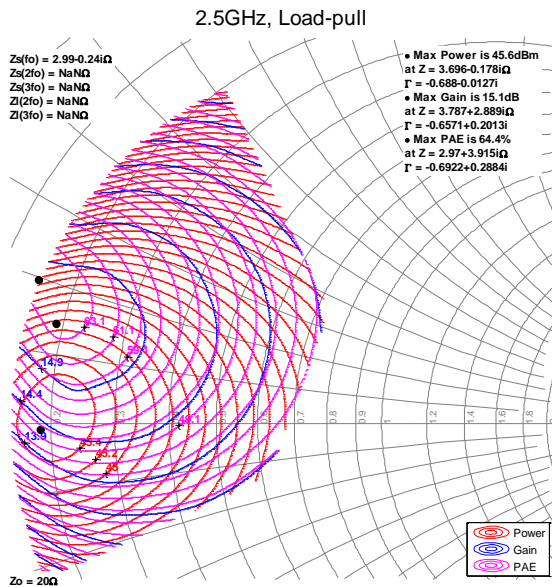
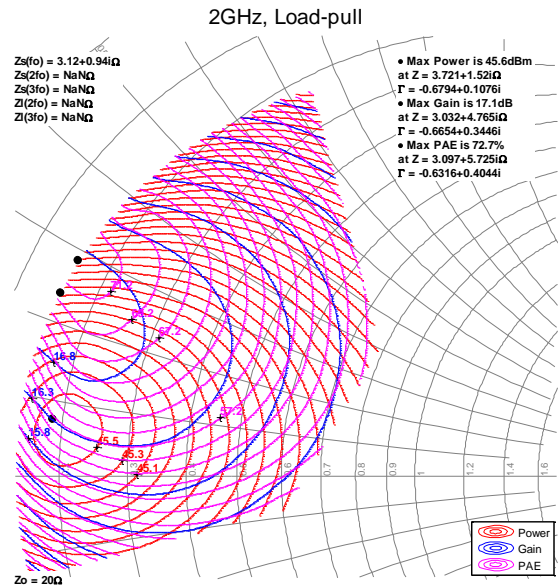
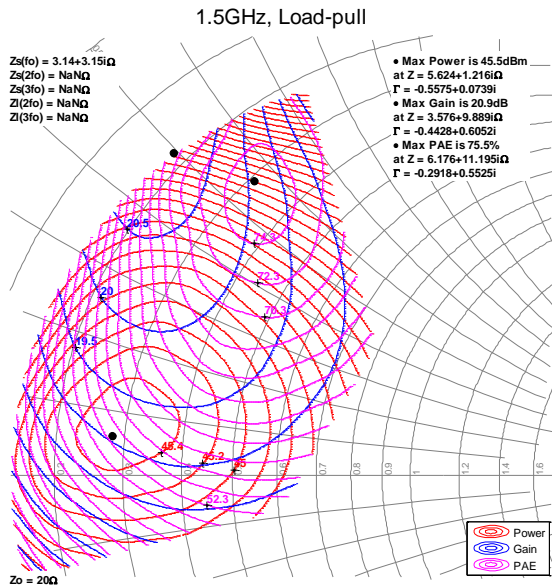


Model Load Pull Contours – Pulsed (1,2,3)

RF performance that the device typically exhibits when placed in the specified impedance environment. The impedances are not the impedances of the device, they are the impedances presented to the device via an RF circuit or load-pull system. The impedances listed follow an optimized trajectory to maintain high power and high efficiency.

Notes:

1. 32 V, 65 mA, Pulsed signal with 100 uS pulse width and 20% duty cycle. 3 dB compression referenced to peak gain.
2. See page 30 for load pull and source pull reference planes.
3. NaN means the impedances are undefined in load-pull system.

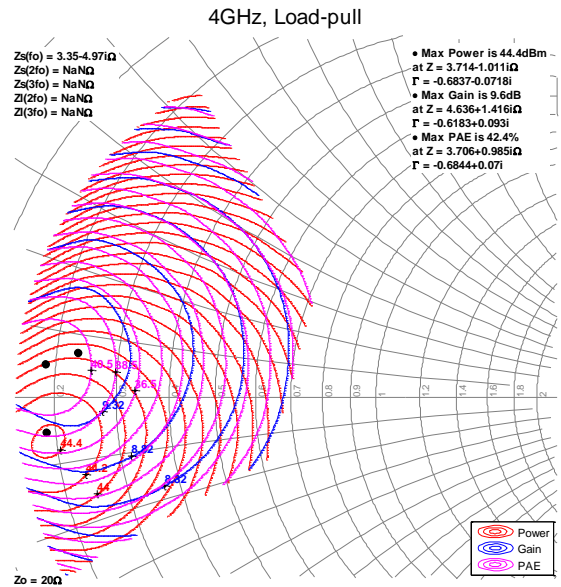
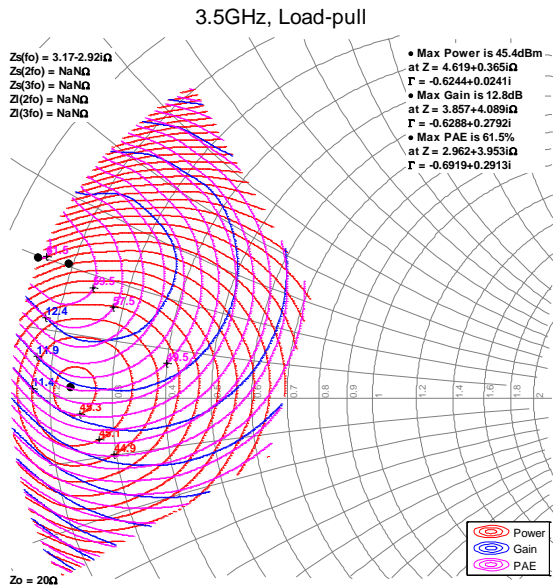


Model Load Pull Contours – Pulsed (1,2,3)

RF performance that the device typically exhibits when placed in the specified impedance environment. The impedances are not the impedances of the device, they are the impedances presented to the device via an RF circuit or load-pull system. The impedances listed follow an optimized trajectory to maintain high power and high efficiency.

Notes:

1. 32 V, 65 mA, Pulsed signal with 100 uS pulse width and 20% duty cycle. 3 dB compression referenced to peak gain.
2. See page 28 for load pull and source pull reference planes.
3. NaN means the impedances are undefined in load-pull system.

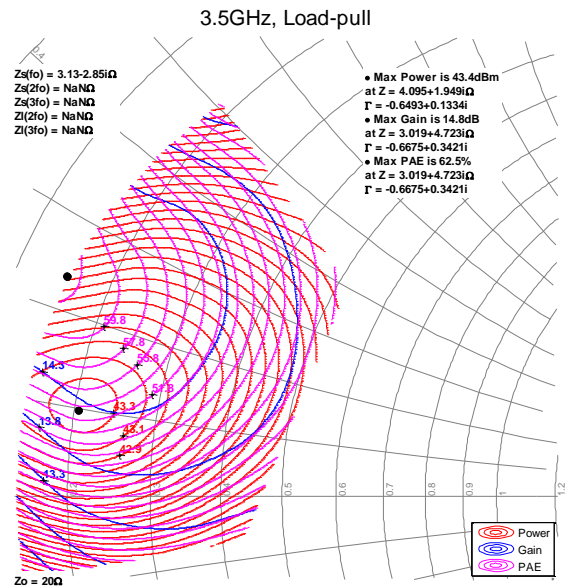
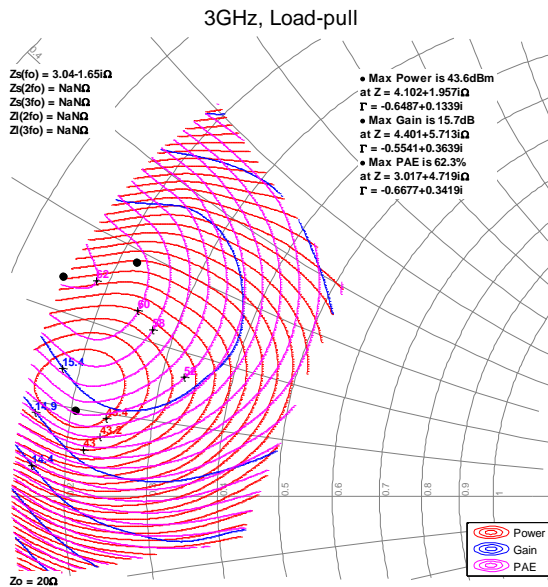
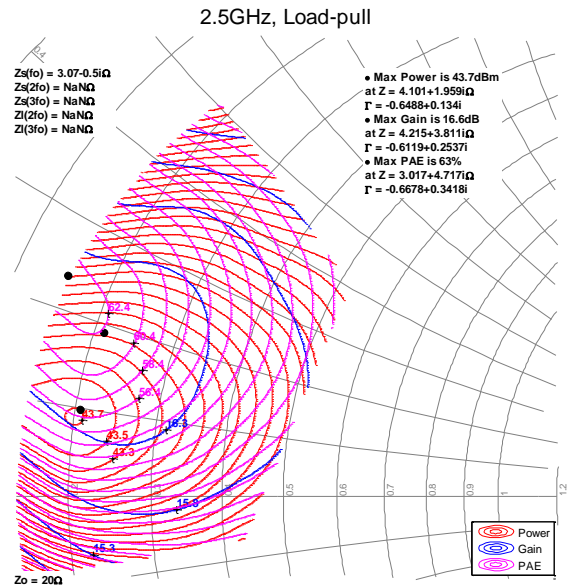
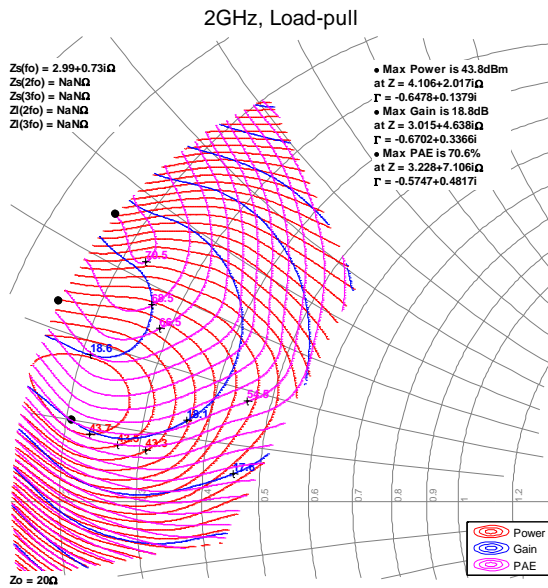


Model Load Pull Contours – CW (1,2,3)

RF performance that the device typically exhibits when placed in the specified impedance environment. The impedances are not the impedances of the device, they are the impedances presented to the device via an RF circuit or load-pull system. The impedances listed follow an optimized trajectory to maintain high power and high efficiency.

Notes:

1. 32 V, 65 mA. 1 dB compression referenced to peak gain.
2. See page 28 for load pull and source pull reference planes.
3. NaN means the impedances are undefined in load-pull system.

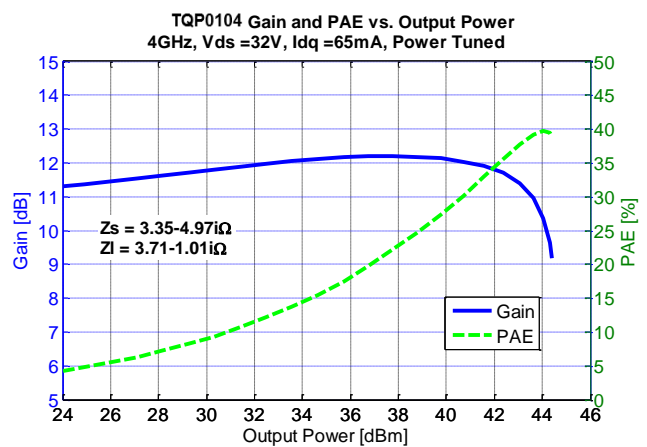
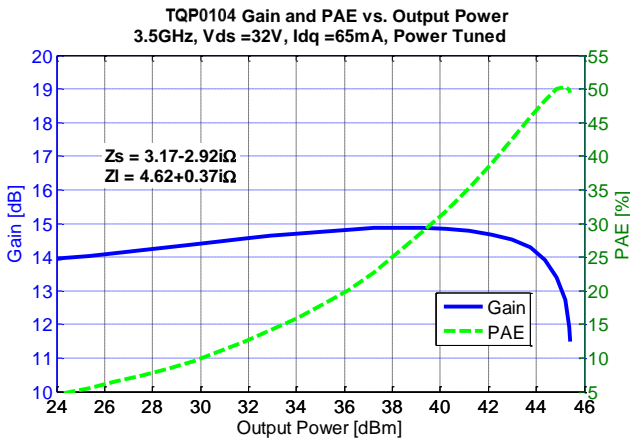
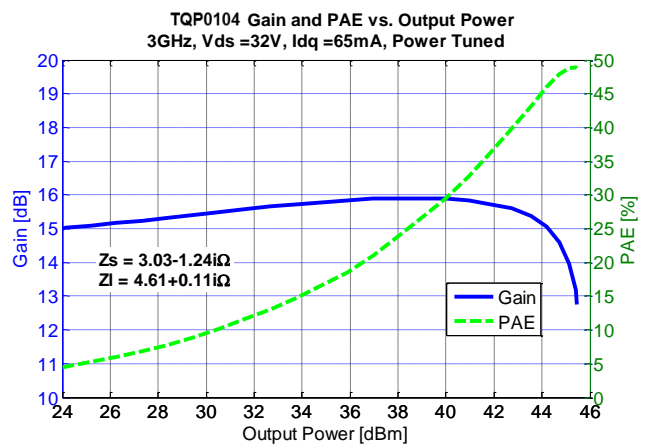
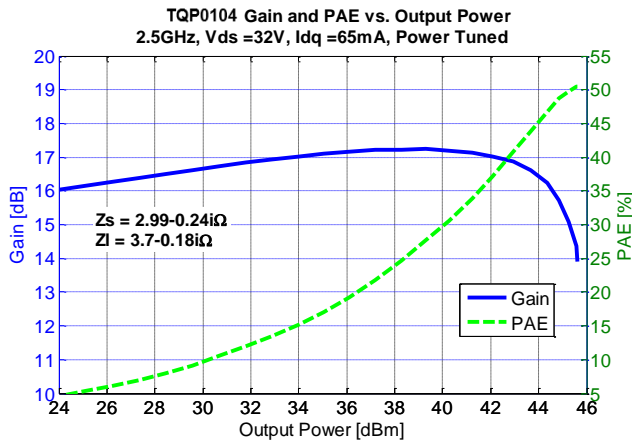
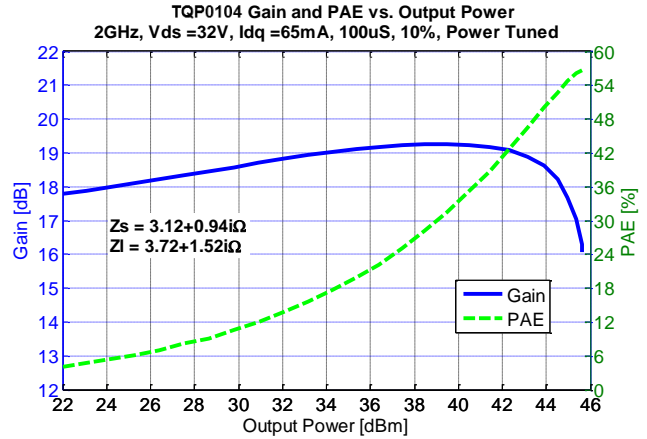
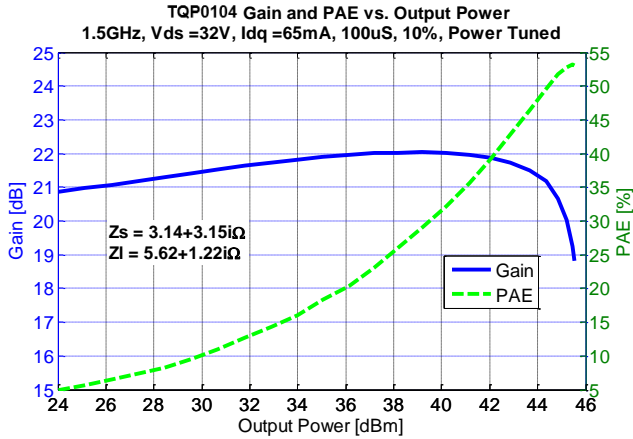




Typical Pulsed Performance – Power Tuned <sup>(1)</sup>

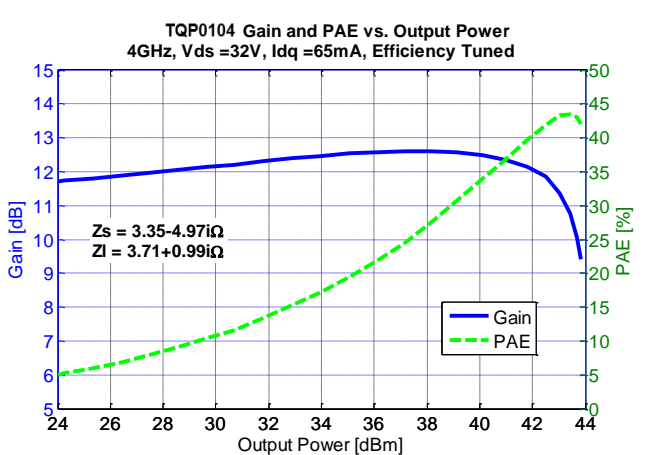
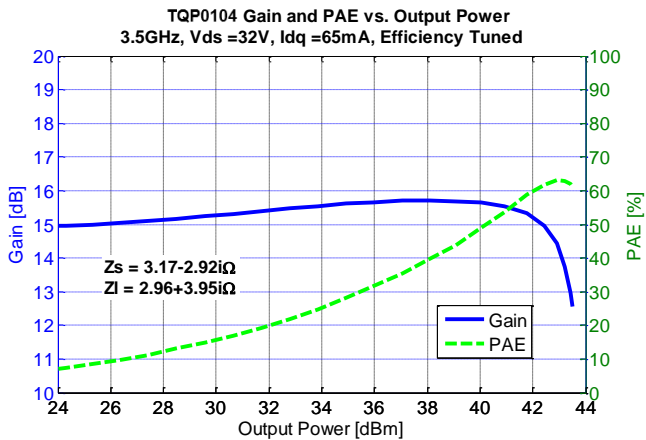
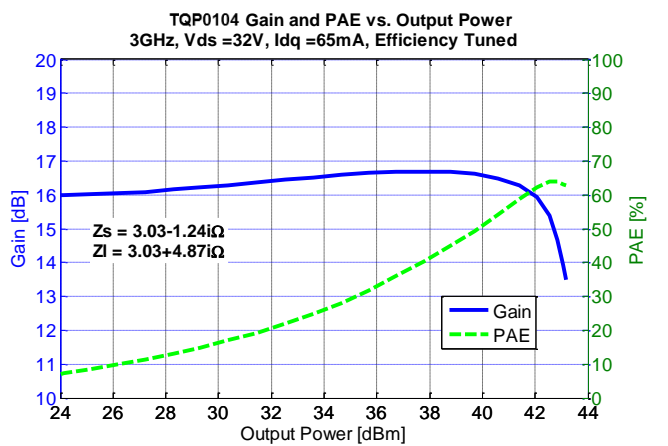
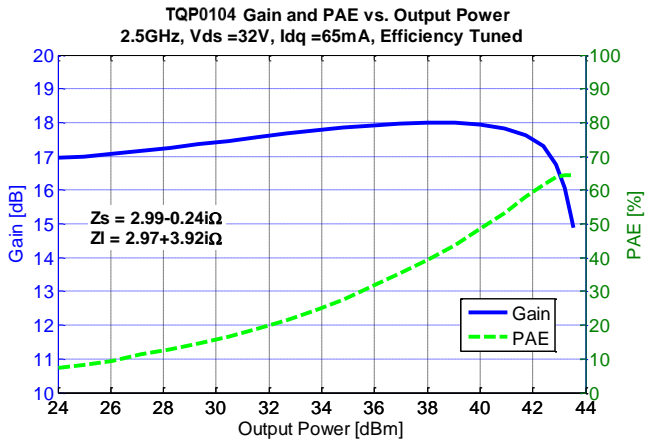
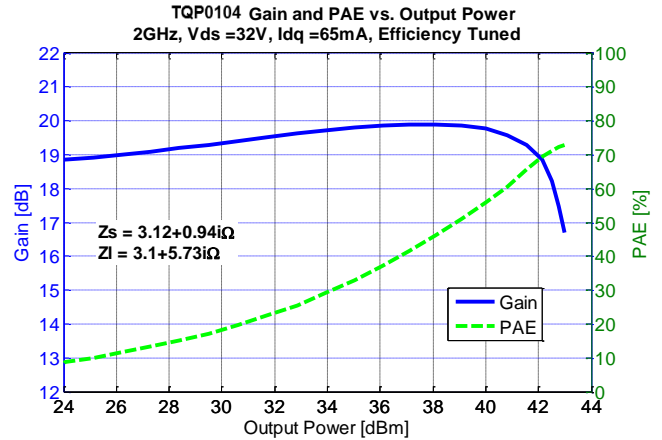
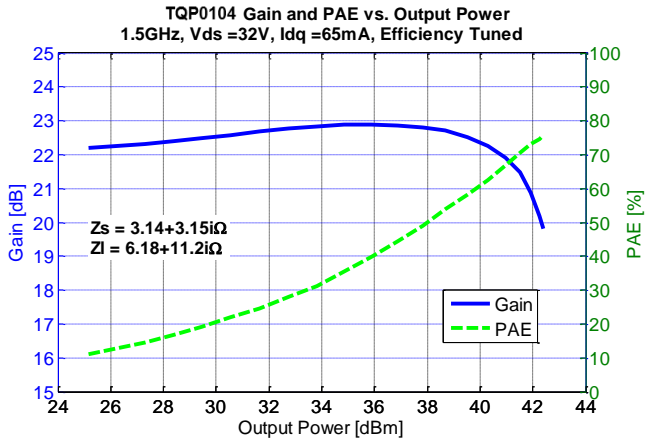
Notes:

1. Pulsed signal with 100 uS pulse width and 10% duty cycle

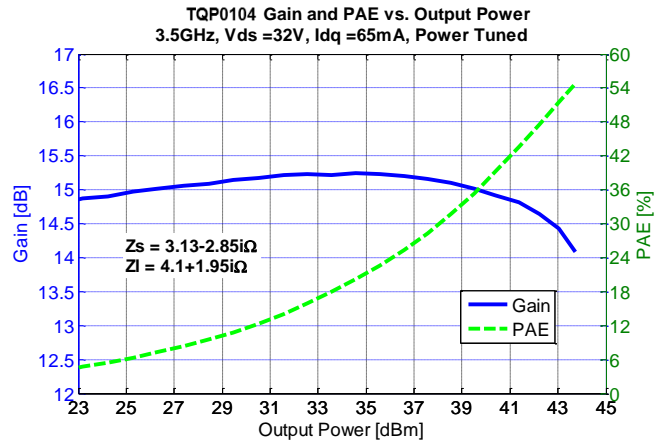
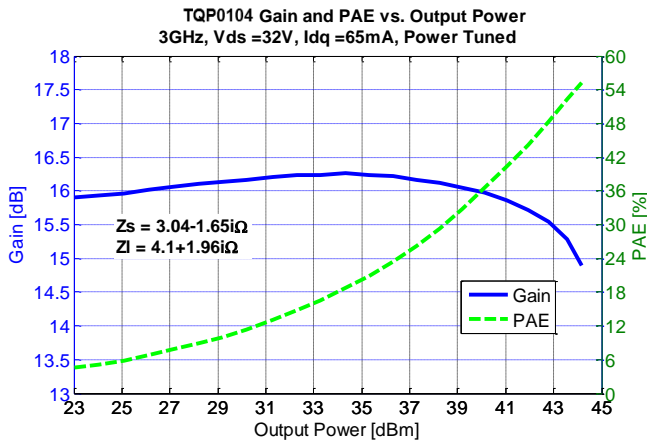
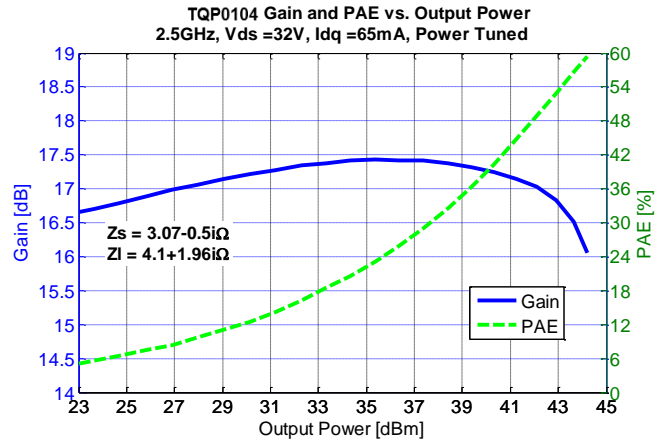
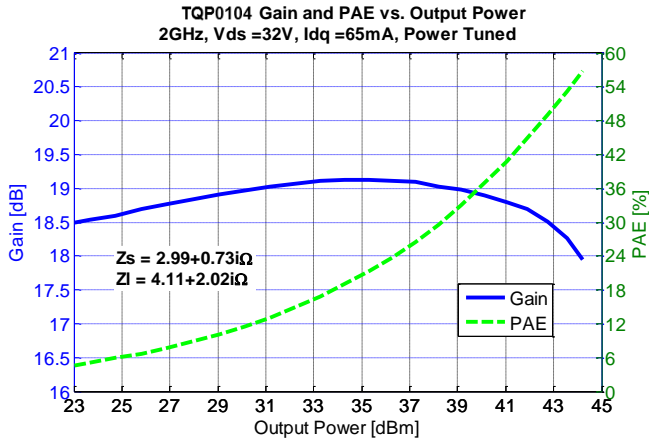


Typical Pulsed Performance – Efficiency Tuned <sup>(1)</sup>

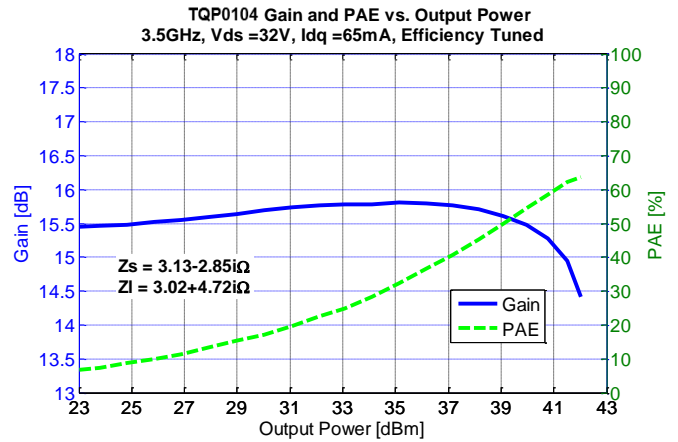
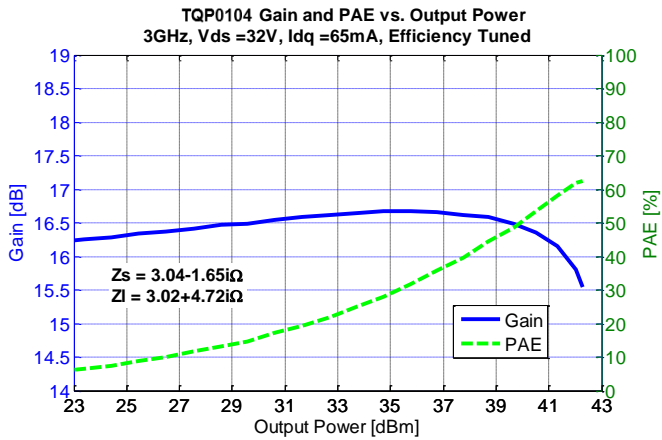
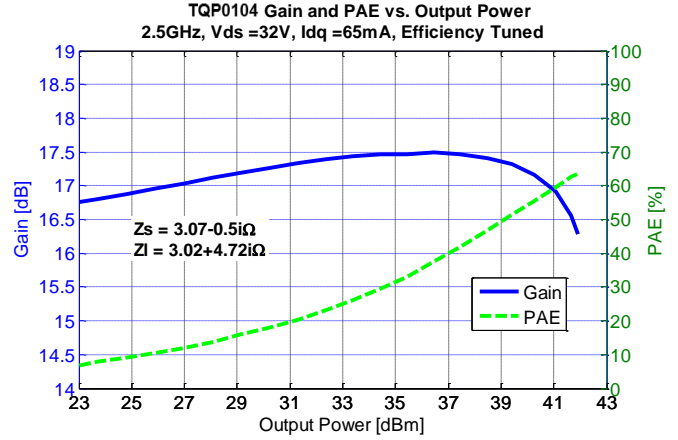
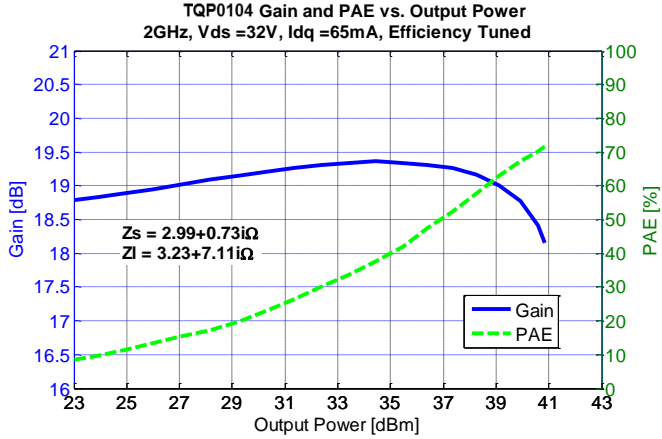
Notes:  
Pulsed signal with 100 uS pulse width and 10% duty cycle



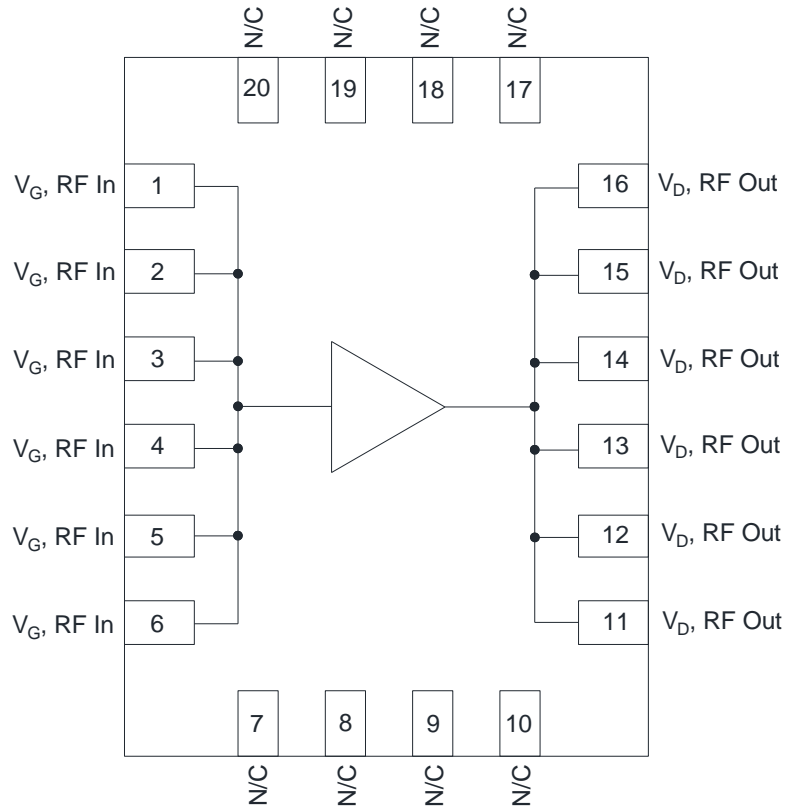
Typical CW Performance – Power Tuned (1)



Typical CW Performance – Efficiency Tuned (1)



## Pin Layout

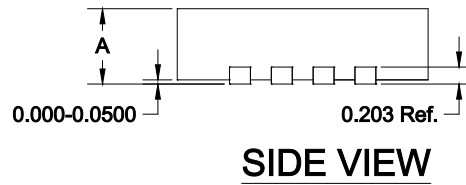
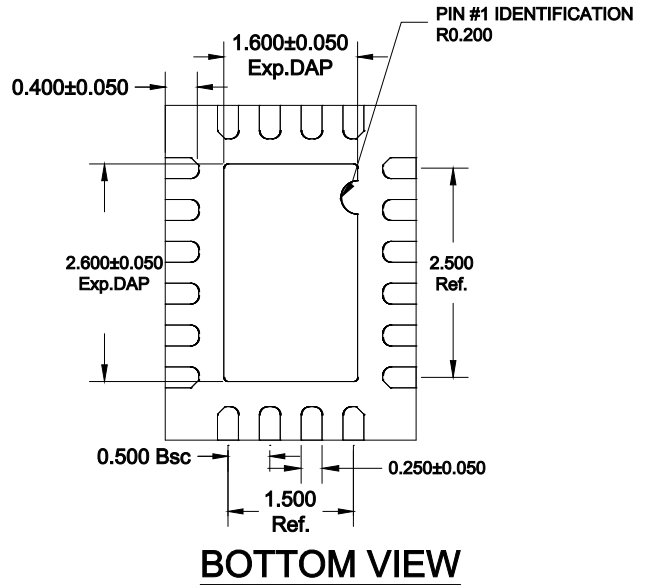
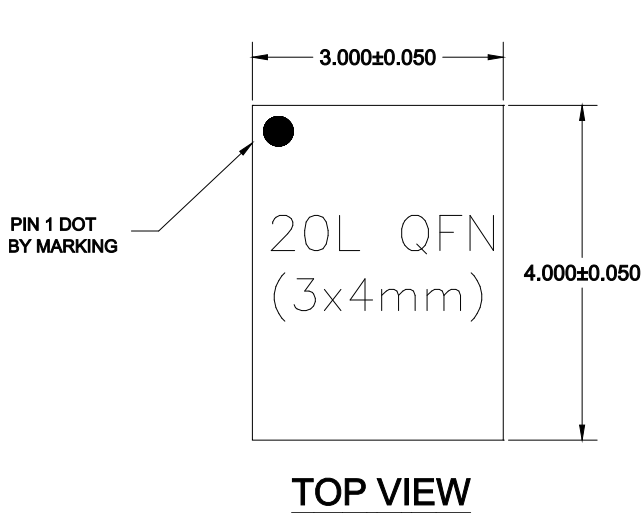


## Pin Description

Pin	Symbol	Description
11 - 16	$V_D$ / RF OUT	Drain voltage / RF Output
1 - 6	$V_G$ / RF IN	Gate voltage / RF
7 – 10, 17 - 20	NC	Not connected
Back side	Source	Source connected to ground

**Mechanical Information**

All dimensions are in millimeters.

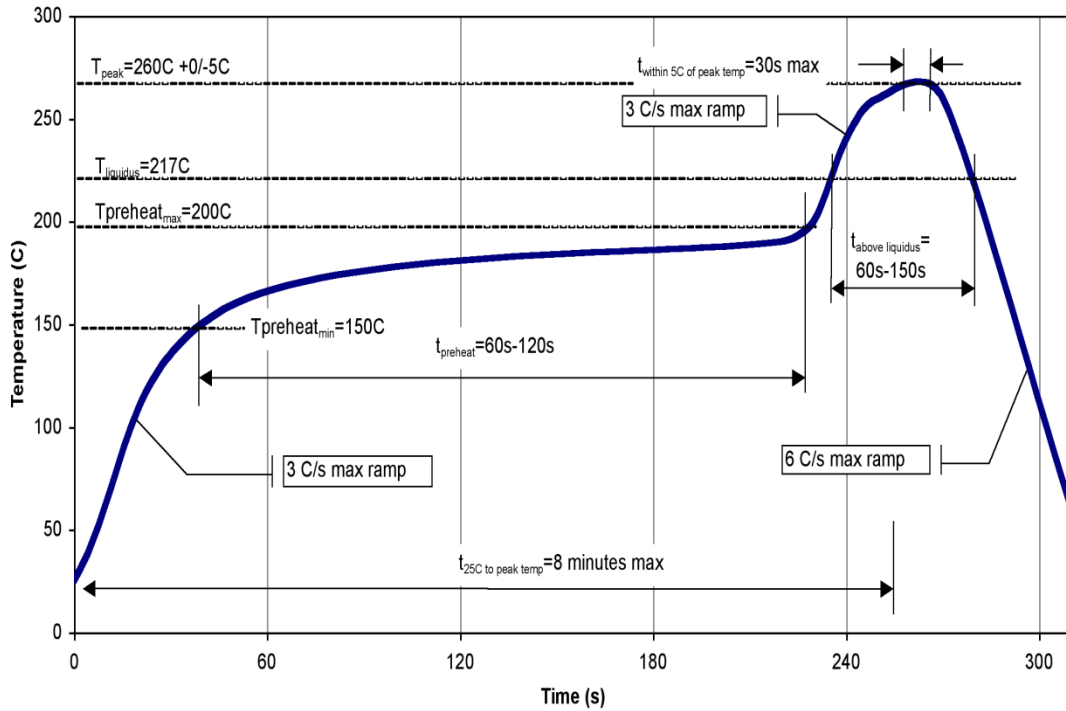


<b>A</b>	MAX.	QFN 0.900
	NOM.	0.850
	MIN.	0.800

**Note:**

Unless otherwise noted, all dimension tolerances are +/-0.127 mm.  
 This package is lead-free/RoHS-compliant. The plating material on the leads is NiPdAu. It is compatible with both lead-free (maximum 260 °C reflow temperature) and tin-lead (maximum 245°C reflow temperature) soldering processes.

Recommended Soldering Temperature Profile



## Handling Precautions

Parameter	Rating	Standard
ESD – Human Body Model (HBM)	Class 1B	ANSI/ESD/JEDEC JS-001
ESD – Charged Device Model (CDM)	Class C3	ANSI /ESD/JEDEC JS-002
MSL – Moisture Sensitivity Level	Level 3	IPC/JEDEC J-STD-020



## Solderability

Compatible with the latest version of J-STD-020, Lead free solder, 260 °C

## RoHS Compliance

This part is compliant with 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment) as amended by Directive 2015/863/EU.

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A (C<sub>15</sub>H<sub>12</sub>Br<sub>4</sub>O<sub>2</sub>) Free
- PFOS Free
- SVHC Free



## Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations:

Web: [www.qorvo.com](http://www.qorvo.com)

Tel: 1-844-890-8163

Email: [customer.support@qorvo.com](mailto:customer.support@qorvo.com)

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